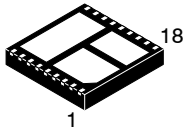


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

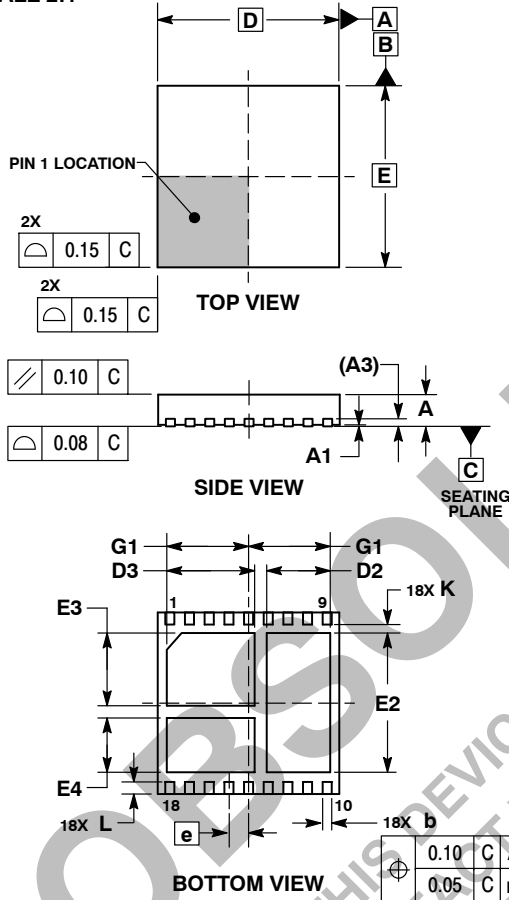
ON Semiconductor®



SCALE 2:1

DFN18
CASE 506BD
ISSUE A

DATE 17 DEC 2019



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	0.90
A1	0.00	0.05
A3	0.20	REF
b	0.25	0.35
D	6.00	BSC
D2	2.05	2.15
D3	2.85	2.95
E	6.00	BSC
E2	4.55	4.65
E3	2.35	2.45
E4	1.80	1.90
e	0.65	BSC
G1	2.65	2.75
K	0.20	MIN
L	0.35	0.45

OBSOLETE

THIS DEVICE IS OBSOLETE. YOUR ON SEMICONDUCTOR REPRESENTATIVE FOR INFORMATION

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	18 PIN DFN, 6X6 MM. 0.65 MM PITCH	PAGE 1 OF 2

